


MATERIAL DECLARATION SHEET



Material Number	CC453232 Series			
Product Line	Wound Chip Inductor			
Compliance Date	2020 / 04 / 09			
RoHS Compliant	Yes	MSL	3	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Ferrite Material	Ferrite	0.03	Iron oxide (Fe2O3)	1309-37-1	63.0	17.19	27.274
				Nickel oxide (NiO)	1313-99-1	12.0	3.27	
				Zinc oxide (ZnO)	1314-13-2	18.0	4.91	
				Copper oxide(CuO)	1317-38-0	7.0	1.91	
2	Winding Wire	Copper	0.015	Copper (Cu)	7440-50-8	95.0	12.95	13.636
				Polyester Resin	9009-54-5	5.0	0.68	
3	Terminal	Copper	0.035	Copper (Cu)	7440-50-8	95.0	30.23	31.818
				Tin (Sn)	7440-31-5	5.0	1.59	
4	Adhesive	Adhesive	0.013	Poly[(phenyl glycidyl ether)-co-formaldehyde]	28064-14-4	65.0	7.68	11.818
				2-Methylimidazole	693-98-1	6.0	0.71	
				Toluene	108-88-3	6.0	0.71	
				Carbon black	1333-86-4	4.0	0.47	

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				Silicon dioxide	7631-86-9	19.0	2.25	
5	Adhesive	Adhesive	0.006	Bisphenol A diglycidyl ether	25068-38-6	81.0	4.42	5.455
				1,4-Butanediol diglycidyl ether	2425-79-8	18.0	0.98	
				Additives	-	1.0	0.05	
		Adhesive	0.003	Methyltetrahydrophthalic anhydride	26590-20-5	95.0	2.59	2.727
				2,4-dimethyl-1H-imidazole	930-62-1	5.0	0.14	
6	Molding Compound	Silica & Epoxy	0.005	silica	60676-86-0	69.0	3.14	4.545
				Sb ₂ O ₃	1309-64-4	2.5	0.11	
				Formaldehyde, polymer with 2-(chloromethyl)oxirane and 2-methylphenol	29690-82-2	15.0	0.68	
				Phenol-Formaldehyde Resin	9003-35-4	10.0	0.45	
				Brominated epoxy resin	40039-93-8	2.5	0.11	
				Carbon black	1333-86-4	1.0	0.05	
7	Solder	Tin	0.003	Tin (Sn)	7440-31-5	100.0	2.73	2.727
		Total weight	0.11					

This Document was updated on: **2020/04/09**

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.

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- a. "Compliance Date" is not the date supplier submits the MDS, but when the product was first compliant with RoHS.
- b. "This Document was updated on:" is where we indicate when supplier submits the MDS. All previous MDS must be archived for traceability in the future.
- c. Material weights for components less than 100mg (most Semiconductor products) should be listed in milligrams. This avoids all those zeros and round off issues.